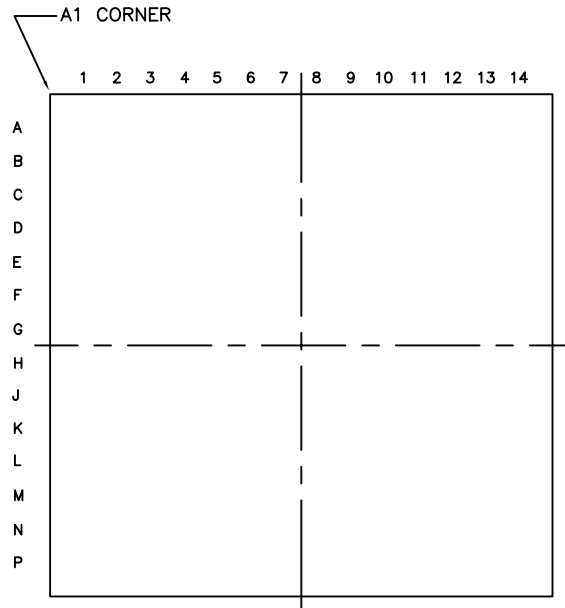
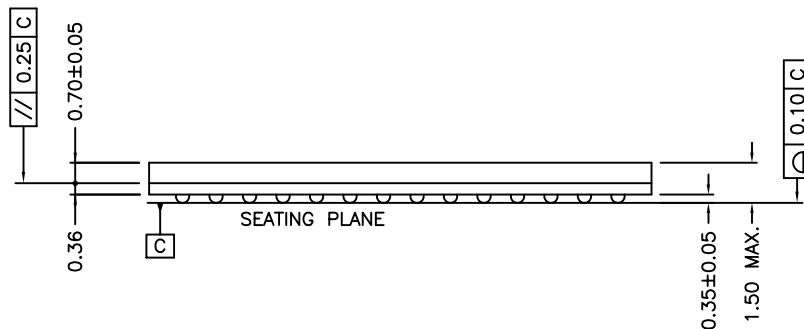
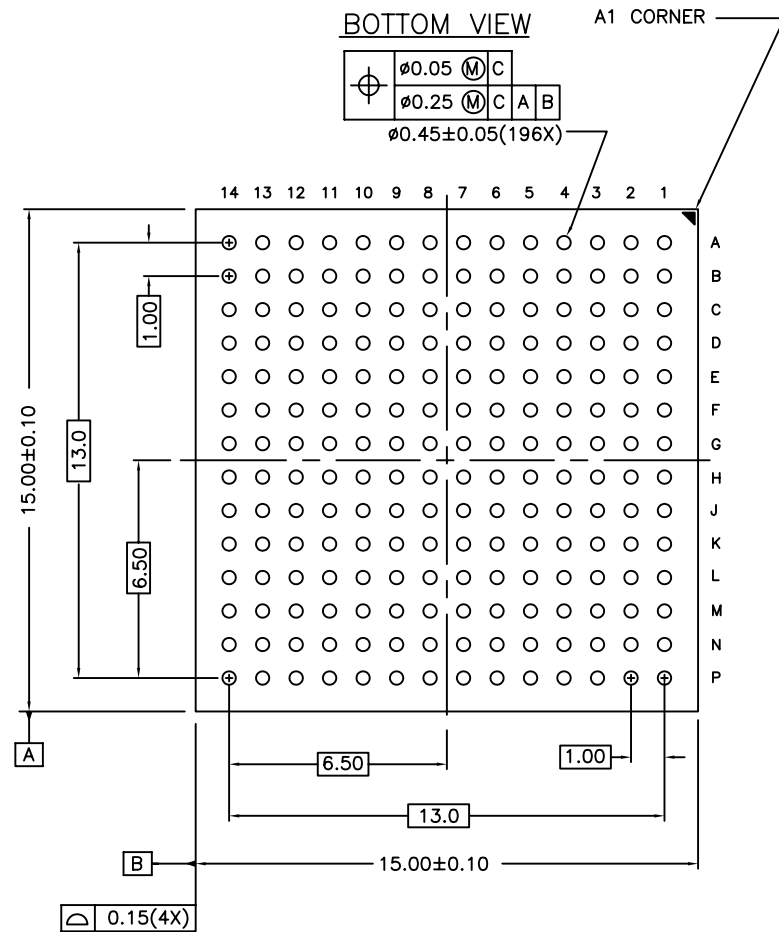


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	112416	NEW RELEASE	12/19/01	N/A
1	-	*A	115633	ADD SUBSTRATE DIM./ ADD MOLD CAP DIM./ CHG. BALL HEIGHT DIM./ CHG. PKG. BODY TOLERANCE	05/14/02	N/A
1	-	*B	2811684	Changed Template and Title from 196 FBGA (15x15x1.5MM) PKG. OUTLINE to PACKAGE OUTLINE, 196L FBGA 15X15X1.5 MM BB196A.	11/20/09	QAD
1	-	*C	3351957	Update spec for sunset review, no changed	8/23/11	QAD
1	-	*D	3722696	ADDED "PKG WEIGHT: REFER TO PMDD SPEC".	8/24/12	QAD


TOP VIEW



BOTTOM VIEW



PKG WEIGHT: REFER TO PMDD SPEC

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 05/14/02	 <div>CYPRESS Company Confidential</div>				
	DRAWN BY HTN	DATE 05/14/02					
	CHECKED BY EDCA	DATE 08/24/12					
	APPROVED BY QAD	DATE 08/24/12					
MATERIAL N/A	APPROVED BY ZZQ	DATE 08/24/12	TITLE PACKAGE OUTLINE, 196L FBGA 15X15X1.5 MM BB196A				
FINISH N/A	APPROVED BY CMG	DATE 08/24/12	SIZE A	PART NO. BB196A	DWG NO 51-85156	REV *D	
			SCALED TO FIT		N/A		SHEET 1 OF 1

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